

Amendments to the Claims

Claim 1 (previously amended): A calibration method for a test system wherein semiconductor components are tested by making contact with a component to be tested via a probe card, the method which comprises:

providing a test substrate having mutually separated connecting contact points for a probe of a probe card, having mutually separated further connecting contact points for a reference probe, and having conductor tracks each connecting one of the connecting contact points to a respective one of the further connecting contact points to define contact point pairs;

placing a probe of a probe card on a connecting contact point and placing a reference probe onto the further connecting contact point of a respective contact point pair; and

calibrating the test system, including the probe card, by using the reference probe as a reference point for a respective signal path and adjusting the signal path to obtain same propagation-times for all signals.

Claim 2 (original): The method according to claim 1, which comprises placing the test substrate into a holder and indexing the test substrate onward, to connect the probes

belonging to a probe card successively to various connecting contact points on the test substrate.

Claim 3 (original): The method according to claim 2, wherein the indexing step comprises moving the holder together with the test substrate.

Claim 4 (original): The method according to claim 2, wherein the indexing step comprises moving the test substrate in the holder onward.

Claim 5 (original): The method according to claim 1, wherein the providing step comprises providing a test substrate having conductor tracks between connecting contact point and the further connecting contact point of a contact point pair of approximately the same length.

Claim 6 (original): The method according to claim 1, wherein the providing step comprises providing a test substrate having the further connecting contact points arranged in a straight line.

Claim 7 (cancelled).